



IC Packaging Markets

2019 Global Report Series

Complex multi-component and multi-layered packages have added a new dimension of cost and high speed performance to integrated circuits (ICs), thus enabling IC packaging to be a game changer for the electronics manufacturing industry overall. It is the IC's package that enables complex multi-component devices to drive the myriad applications for modern electronics in today's emerging markets.

New Venture Research (NVR) is pleased to announce its continuing coverage of the IC packaging market with two new reports in 2019. Each report examines the global IC devices and packaging markets from a different vantage point, thus allowing the reader to analyze the world of IC packaging from a number of market perspectives, in order to meet individual market research needs.

The first report, **The Worldwide OSAT and Semiconductor Applications Market–2019 Edition**, expands on NVR's worldwide IC packaging market data, but for the first time examines in detail ICs and packaging by major applications segments (Consumer, Computer, Communications, Automotive and

Industrial & Other), as well as focusing on several specific product markets (e.g., cellular handsets, tablets, PCs, etc.). The report also presents NVR's continuing extensive coverage of the evolving outsourced semiconductor assembly and test (OSAT) contractor market.

The second report, **The Worldwide Conventional and Advanced Packaging Market for IC Devices–2019 Edition**, analyzes the major IC device types by world region and by packaging type. It provides details of the major conventional packaging types with a breakdown by I/O count, as well as advanced packaging such as SiP, PoP and PiP. Also covered is an extensive discussion of flip chip packaging.

In addition to extensive descriptions of the many IC industry market segments, both reports provide dozens of tables and figures with historical data and forecasts of market size by unit shipments, annual revenues and unit pricing from 2018 through 2023. Please review each report's summary Table of Contents on the following page for more detail.

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The Worldwide OSAT and Semiconductor Applications Markets - 2019 Edition

Chapter 1: Introduction

Chapter 2: Executive Summary

Chapter 3: Overview of the Worldwide IC Packaging Markets

Chapter 4: OSAT Market and Strategy Analysis

Chapter 5: IC Applications Analysis

Chapter 6: OSAT Company Profiles

Published June 2019, 300+ pages

The Worldwide Conventional and Advanced Packaging Markets for IC Devices - 2019 Edition

Chapter 1: Introduction

Chapter 2: Executive Summary

Chapter 3: Worldwide Electronics Industry Outlook

Chapter 4: Semiconductor Device Market Analysis

Chapter 5: Flip Chip Market Analysis

Chapter 6: IC Packaging Market Analysis

Chapter 7: Advanced Packaging Markets

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About the Author

Jerry Watkins is an independent senior analyst with more than 20 years of experience in the field of market research and consulting. He has worked for leading research companies such as Frost & Sullivan, Lucid Information Services, and NSI Research both in management and as a writer. Mr. Watkins has authored many syndicated reports, previously in the telecommunications sector and more recently in the computing, merchant embedded computing industry, as well as two IC packaging related reports in since 2014. He holds two university degrees including a B.A. in History, as well as a M.A. in International Studies.